

Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (original) A glass substrate machining method comprising the steps of:

machining a glass substrate by using a CO<sub>2</sub> laser of variable pulse width as machining means;

a first step of executing a single laser irradiation; and

a second step of executing a plurality of laser irradiations.

2. (original) The glass substrate machining method according to claim 1, wherein the pulse width of said laser in the second step is greater than that in the first step.

3. (original) A high-frequency circuit fabricating method comprising

machining a glass substrate by using a CO<sub>2</sub> laser;

controlling an amount of air bubbles in said glass substrate to improve the workability of said glass substrate.

4. (original) A high-frequency circuit fabricating method according to claim 3, comprising forming a thin insulator on a glass surface.

5. (original) A high-frequency circuit fabricating method according to claim 3, wherein an internal cavity is formed within said glass substrate.

6. (original) A high-frequency circuit fabricating method according to claim 3, wherein said glass substrate, after said laser machining, has a large surface area in the machined surface due to bubble traces in glass; and

forming a metal film through simple electroless plating, to improve heat radiation property of the metal film-formed portion.

7-18. (canceled)